

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3924468

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	PATENT RELEASE	
CONVEYING PARTY DATA		
Name		Execution Date
MORGAN STANLEY SENIOR FUNDING, INC.		06/03/2016
RECEIVING PARTY DATA		
Name:	NXP B.V.	
Street Address:	HIGH TECH CAMPUS 60	
Internal Address:	5656 AG	
City:	EINDHOVEN	
State/Country:	NETHERLANDS	
PROPERTY NUMBERS Total: 22		
Property Type	Number	
Patent Number:	8378593	
Application Number:	12989822	
Patent Number:	8593772	
Patent Number:	8664885	
Patent Number:	8653750	
Patent Number:	9137880	
Patent Number:	8723444	
Patent Number:	9128500	
Patent Number:	8692479	
Application Number:	13868501	
Patent Number:	8963511	
Patent Number:	8836226	
Patent Number:	9167638	
Patent Number:	8878444	
Application Number:	14279497	
Patent Number:	9301352	
Application Number:	14564659	
Patent Number:	9271355	
Application Number:	14714059	
Application Number:	14713982	

PATENT

Property Type	Number
Application Number:	14995347
Patent Number:	6876036

CORRESPONDENCE DATA

Fax Number: (800)494-7512

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 202-370-4750

Email: ipteam@nationalcorp.com

Correspondent Name: JOANNA MCCALL

Address Line 1: 1025 VERMONT AVE NW, SUITE 1130

Address Line 2: NATIONAL CORPORATE RESEARCH, LTD

Address Line 4: WASHINGTON, D.C. 20005

ATTORNEY DOCKET NUMBER:	F163826
NAME OF SUBMITTER:	RICK HARRISON
SIGNATURE:	/Rick Harrison/
DATE SIGNED:	06/17/2016

Total Attachments: 4

source=#88520778v1 - (Patent Release sent for filing 6-17-16)#page2.tif

source=#88520778v1 - (Patent Release sent for filing 6-17-16)#page3.tif

source=#88520778v1 - (Patent Release sent for filing 6-17-16)#page4.tif

source=#88520778v1 - (Patent Release sent for filing 6-17-16)#page5.tif

PATENT RELEASE

THIS PATENT RELEASE is effective as of June 3, 2016 by Morgan Stanley Senior Funding, Inc., as the Collateral Agents (as defined below).

1. Reference is made to:

- (a) that certain Secured Term Credit Agreement, dated as of March 4, 2011 (as amended, supplemented or otherwise modified from time to time, the "Term Credit Agreement") and together with the Revolving Credit Agreement, the "NXP Credit Agreements") entered into by NXP Semiconductors N.V. (previously KASLION Acquisition B.V.) with its corporate seat in Eindhoven, the Netherlands ("Holdings"), NXP B.V. (the "Company"), certain affiliates of the Company, the Secured Parties, Morgan Stanley Senior Funding, Inc., as Global Collateral Agent (in such capacity, the "Global Collateral Agent") and as RCF Administrative Agent (in such capacity, the "RCF Administrative Agent") and in its capacities as 5% Notes Collateral Agent, 6% Notes Collateral Agent and Credit Agreement Collateral Agent (the "Notes Collateral Agent") and Mizuho Bank Ltd. (formerly Mizuho Corporate Bank Ltd.), as Taiwan Collateral Agent (in such capacity, the "Taiwan Collateral Agent") and, together with the Global Collateral Agent, and the Notes Collateral Agent, the "Collateral Agents") for the Secured Parties under the Collateral Agency Agreement referred to below, and others;
- (b) (i) that certain secured term credit agreement, dated as of December 7, 2015 (as amended, supplemented or otherwise modified from time to time, the "New Term Credit Agreement") and (ii) a secured revolving credit agreement, dated as of December 7, 2015 (as amended, supplemented or otherwise modified from time to time, the "New Revolving Credit Agreement") and together with the New Term Credit Agreement, the "New Credit Agreements") entered into by the Company, NXP Funding LLC, the Secured Parties, the Global Collateral Agent, and others;
- (c) that certain amended and restated indenture in relation to an issue of 5.0% senior secured notes due 2021 (the "Freescale 2021 Notes"), by and among Freescale Semiconductor, Inc., as issuer, NXP B.V., NXP Funding LLC, NXP Semiconductors Netherlands B.V., NXP Semiconductors UK Limited, NXP Semiconductors USA, Inc., NXP Semiconductors Germany GmbH, NXP Semiconductors Hong Kong Limited, NXP Semiconductors Philippines Inc., NXP Semiconductors Singapore Pte. Ltd., NXP Semiconductors Taiwan Ltd., NXP Manufacturing (Thailand) Ltd., Freescale Semiconductor, Ltd., Freescale Semiconductor Holdings II, Ltd., Freescale Semiconductor Holdings III, Ltd., Freescale Semiconductor Holdings IV, Ltd., Freescale Semiconductor Holdings V, Inc. and SigmaTel, LLC, as guarantors (the "Freescale Notes Guarantors") and The Bank of New York, Mellon Trust Company, N.A., as trustee (the "Amended and Restated Indenture for the Freescale 2021 Notes"); and
- (d) that certain amended and restated indenture in relation to an issue of 6.0% senior secured notes due 2022 (the "Freescale 2022 Notes"), by and among Freescale Semiconductor, Inc., as issuer, the Freescale Notes Guarantors and Wells Fargo Bank, National Association, as trustee (the "Amended and Restated Indenture for the Freescale 2022");

Notes" and together with the Amended and Restated Indenture for the Freescale 2021 Notes, the "Amended and Restated Freescale Indentures").

2. The Company has informed the Collateral Agents that it has disposed of the patents listed on Schedule I attached hereto (the "Patents") in a transaction permitted under the Term Credit Agreement, the New Credit Agreements, and the Amended and Restated Freescale Indentures.

3. Accordingly, effective as of the date upon which the following conditions have been satisfied, and based upon the representations provided by the Company, the Collateral Agents' interests (including security interests) in and to the Patents are irrevocably and unconditionally terminated, released, reassigned and extinguished:

(a) The receipt by each Collateral Agent of a fully executed copy of the agreement pursuant to which the Company and/or its subsidiaries intends to sell the patents listed on Schedule I hereto (the "Agreement");

(b) All conditions to the disposal of the Patents contemplated by the Agreement (other than the release of the security interests contemplated hereby and any conditions required to be fulfilled after the effectiveness of the Agreement) shall have been satisfied.


4. Notwithstanding anything herein (or in any other document, communication or filing relating hereto by any person) to the contrary, each Collateral Agent is authorizing solely the release of the liens granted to it in connection with the Term Credit Agreement, the New Credit Agreements, and the Amended and Restated Freescale Indentures and not any other liens or security interests at any time granted by any party in favor of any Collateral Agent pursuant to any other document or in favor of any other person.

5. GOVERNING LAW. THIS RELEASE AGREEMENT SHALL BE GOVERNED BY, AND CONSTRUED AND INTERPRETED IN ACCORDANCE WITH, THE LAWS OF THE STATE OF NEW YORK.


[Remainder of page intentionally left blank]

IN WITNESS WHEREOF, the undersigned have caused this Patent Release to be duly executed and delivered as of the date first above written.


MORGAN STANLEY SENIOR
FUNDING, INC., as Global Collateral
Agent

By: 
Name: Lisa Hansen
Title: Authorized Signatory

MORGAN STANLEY SENIOR
FUNDING, INC., as RCF
Administrative Agent

By: 
Name: Lisa Hansen
Title: Authorized Signatory

MORGAN STANLEY SENIOR
FUNDING, INC., as the Notes
Collateral Agent

By: 
Name: Lisa Hansen
Title: Authorized Signatory

Schedule 1

Holder	Patent No./ (Application No.)	Description/Title
NXP B.V.	US8378593	Jitter correction for LED driver connected to conventional phase cut dimmer.
NXP B.V.	12/989822	Dimming range enhancement for LED driver connected to conventional phase cut dimmer.
NXP B.V.	US8593772	IC compatible with mains voltage enabling a breakthrough for (retrofit) mains voltage LD lighting solutions.
NXP B.V.	US8664885	A CIRCUIT FOR A DIMMER
NXP B.V.	US8653750	Method to detect dimmer and to adapt dynamic dimmer load in order to improve dimmer compatibility and to increase system efficiency.
NXP B.V.	US9137880	Accurate Dimming Control Level Generation from Phase Cut Dimmer Output with Fast Response to Changes in Dimmer Position
NXP B.V.	US8723444	multi output resonant LED driver
NXP B.V.	US9128500	SWITCHING CIRCUITS
NXP B.V.	US8692479	Adaptive digitally controlled dimmable LED lamp driver
NXP B.V.	13/868501	A CONTROL CIRCUIT FOR A PHASE-CUT DIMMER AND A METHOD OF CONTROLLING A PHASE-CUT DIMMER
NXP B.V.	US8963511	Ac main supply recovery with phase looked loop for led driver application
NXP B.V.	US8836226	Soft stop bleeding function to improve dimmer compatibility
NXP B.V.	US9167638	LED CONTROLLER CIRCUIT
NXP B.V.	US8878444	LED current stability improvement via output load control
NXP B.V.	14/279497	Emitter triggered thyristor with separated trigger electrode.
NXP B.V.	US9301352	90Vac or 120Vac input bleeder-less Phase-cut dimming LED drivers
NXP B.V.	14/564659	BJT bleeder for the Off-State and Latching Currents of Phase-Cut Dimmers
NXP B.V.	US9271355	Switching scheme for mains dimmable SSL driver
NXP B.V.	14/714059	Phase-cut dimmable light source without bleeder
NXP B.V.	14/713982	Phase cut control for high side current source LED driver
NXP B.V.	14/995347	Dynamic reduction of LED current in linear LED drivers for fast startup, reduced thermal design constrains and improved load regulation
NXP B.V.	US6876036	SENSING SWITCHING PARAMETERS IN A SOI DEVICE

PATENT

RECORDED: 06/17/2016

REEL: 039070 FRAME: 0582